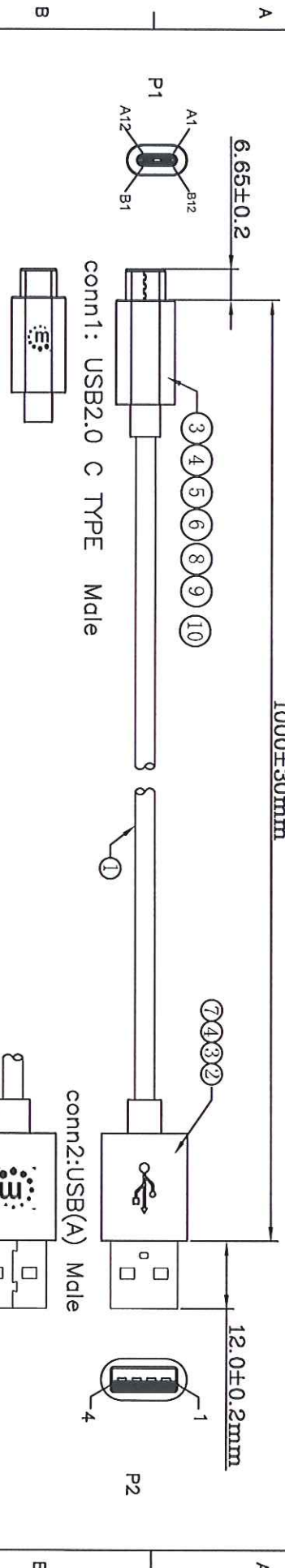
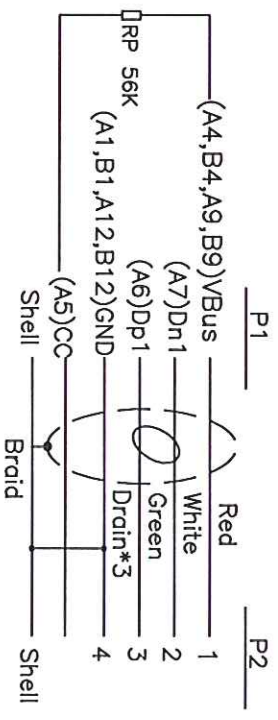
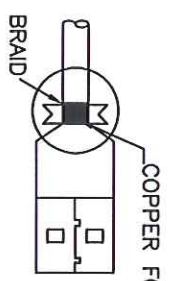
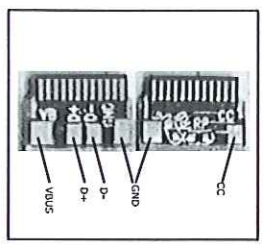


REV.	DESCRIPTION	ENG.	APPROVAL



- Electrical Test:
1. 100%Test(Open ,short ,miss wire)
  2. Contact Resistance: 2 ohm max.
  3. Insulation Resistance: 100M ohm Min.
  4. Hi-Pot: 300VDC/10ms.

TYPE-C PCB pictorial view:



OK.  
Allen Lin 2015.12.3

①	Copper Foil : W=5MM 25u								
②	USB TYPE C n Back Nickel Plated Shell (002, 7*3, 200)	pcs							
③	USB TYPE C n Front Nickel Plated Shell (002, 7*3, 200)	pcs							
④	W=5MM 25u FOIL COPPER	pcs							
⑤	H.S.T 01.0 BLACK	pcs							
⑥	ESD 2.1 C Type Connector Back Insulation Nickel Plated Shell 14.4 (001)(0.05mm(0.004))	pcs							
⑦	Outside Molding: 4SP PVC PMS:BLACK	16							
⑧	Inside Molding: PE	4							
⑨	USB 2.0 AM SOLDER INSULATION:WHITE SHEET NICKEL PLATED	1							
⑩	NICKEL SOLDER THT: 0.75*0.25*0.175*0.25mm(0.0315*0.010*0.007*0.010) (0.0315*0.010*0.007*0.010) 050 0.0315*0.010 Color:BLACK on nickel	1.0							

THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF INTRACOM Asia Co.,Ltd. AND SHALL NOT BE REPRODUCED COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF INTRACOM Asia Co.,Ltd.

UNLESS OTHERWISE SPECIFIED-DIMENSIONS ARE IN MILLIMETERS ANGULAR TOLERANCE:±1°

TOLERANCE(INCH)	TOLERANCE(MM)
X	±0.5mm
X.X	±0.01"
X.XX	±0.02mm
X.XXX	±0.008"
X.XXXX	±0.005"
X.XXXX	±0.15mm
X.XXXX	±0.10mm

**INTRACOM** 安達康股份有限公司  
INTRACOM Asia Co., LTD.

TITLE: MH USB2.0 Cn AM-CM,Black,3.3ft/1m

CUSTOMER: MH

CUSTOMER P/N: 353298

ICT P/N: DWG.ND:

APPD Check Drawer

Unit: mm Projection: 1:1 Size: A4

Scale: 1:1

Sheet: 1 of REV. A06

1 2 3 4 5 6 7